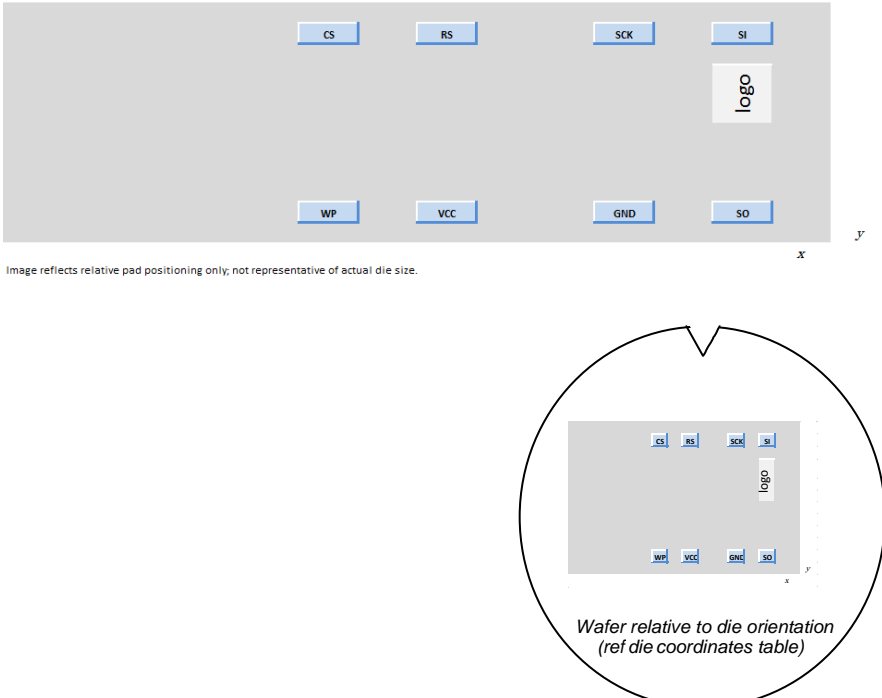


WAFER PRODUCT DATASHEET (ADDENDUM)

Product	AT45DB041E-DWF																																								
Description	4 Mbit, DataFlash, 1.65V – 3.6V VCC																																								
Die Map	 <p>Image reflects relative pad positioning only, not representative of actual die size.</p> <p>Wafer relative to die orientation (ref die coordinates table)</p>																																								
Die Size & Pad Coordinates	<table border="1"> <thead> <tr> <th></th> <th>X (μm)</th> <th>Y (μm)</th> </tr> </thead> <tbody> <tr> <td>Die Size</td> <td>2518</td> <td>1418</td> </tr> <tr> <td>Scribe Line Width</td> <td>80</td> <td>80</td> </tr> <tr> <td>Die Step</td> <td>2598</td> <td>1498</td> </tr> <tr> <td>Pad Opening</td> <td>65</td> <td>65</td> </tr> <tr> <td>SI</td> <td>857.67</td> <td>614.44</td> </tr> <tr> <td>SCK</td> <td>705.26</td> <td>614.44</td> </tr> <tr> <td>RSB</td> <td>20.36</td> <td>614.44</td> </tr> <tr> <td>CSB</td> <td>-258.1</td> <td>614.44</td> </tr> <tr> <td>WPB</td> <td>-98.68</td> <td>-615.85</td> </tr> <tr> <td>VCC</td> <td>223.93</td> <td>-615.85</td> </tr> <tr> <td>GND</td> <td>883.46</td> <td>-615.85</td> </tr> <tr> <td>SO</td> <td>1043.14</td> <td>-615.85</td> </tr> </tbody> </table>			X (μm)	Y (μm)	Die Size	2518	1418	Scribe Line Width	80	80	Die Step	2598	1498	Pad Opening	65	65	SI	857.67	614.44	SCK	705.26	614.44	RSB	20.36	614.44	CSB	-258.1	614.44	WPB	-98.68	-615.85	VCC	223.93	-615.85	GND	883.46	-615.85	SO	1043.14	-615.85
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Technical Details	
Adesto Product Family	DataFlash
Density	4 Mbit
Operating Vcc	1.65V - 3.6V
ESD	>2kV JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	200
Process Geometry (nm)	110
Die ID	637F5
Wafer Map	Electronic- text file
Manufacturing Facility	UMC
Wafer Thickness (µm) Maximum	725
Back Grind Options	None / Contact Adesto
Back Plane Connection	Floating / Not Required
Backside preparation / metallization	None
Bond wire qualified	AU <input checked="" type="checkbox"/> CU <input type="checkbox"/> AG <input type="checkbox"/>
Passivation Material	HDP oxide + SiON
Passivation Thickness (Å)	21000
Bond Pad Material	Ti/TiN/AlCu
Bond Pad Thickness (Å)	6000
Good Die per Wafer	Contact Adesto (AT45DB041E-DWF) ¹
Good Die per Wafer	Contact Adesto (AT45DB041E-DWFHT) ¹
Active Circuits underneath the bond pad	Yes

¹ Average value; subject to change without notice.

Part Number Ordering Code ²	Operating Temperature Range	Functional Specification
AT45DB041E-DWF	-40°C to 85°C	http://www.adestotech.com/wp-content/uploads/doc8783.pdf
AT45DB041E-DWFHT	-40°C to 125°C	http://www.adestotech.com/wp-content/uploads/DS-AT45DB041E-HTADD.pdf

Adesto Technologies Corporation

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² Handle product in accordance with UV and ESD precautions.

Revision Level – Release Date	History
A – August 2015	Initial release.
B – November 2015	Updated wafer orientation in die map image. Added footnote on handling.
C – August 2017	Updated address and contact information.

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